## amecthermaso

## **Micro Porous Finned Ceramic Heat Sink**

**FCH Series** 



## Features

- Light weight
- Non metallic
- Low cost
- Higher power than flat types

The FCH micro porous ceramic finned heat sinks are constructed from entirely new material structure that moves heat by air circulation (without external force). Due to its micro-porous nature it provides a vast surface area compared with traditional heat sinks which ensures highly efficient heat dissipation. A ceramic heat sink is non-electrically conductive, thereby ensuring no antenna effect; light in weight; lower in price compared to aluminium and Copper heat sinks. The special material nature ensure they are not affected by humidity and dust. The extremely strong bond of the adhesive tape means they can be fixed direct to the surface of any IC component and there by reducing assembly time and labour costs. The raised fins provides a greater surface area compared to flat type ceramic heat sinks and therefore a greater power dissipation of up to 10W can be achieved.

Part Number	Length (mm)	Width (mm)	Height (mm)
FH25255T	25+/-0.5	25+/-0.5	5.0+/-0.23
FCH30305T	30+/-0.5	30+/-0.5	5.25+/-023
FCH303512T	35+/-0.5	30+/-0.5	12.25+/-0.23
FCH40405T	40+/-0.5	40+/-0.5	5.25/-0.23
FCH505010T	50+/-0.5	50+/-0.5	10.25+/-0.23
FCH505015T	50+/-0.5	50+/-0.5	15.25+/-0.23

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